ASSOCIATION CO	ONNECTING NDUSTRIES	C, Bannockb	urn, Illinois. A	ll rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat	tion of the ncompared	he substance asses all low	s within the er level mat	manufactur erials for wl	er listed i hich the n	tem. Note: nanufacture	if the item is an as er has engineering	ssembly with low responsibility.	
752-21.1					Form Type Distribute						eous Materia	ials and Mfg Information				
upplier I	nformation															
ompany na	ime*	Company unique ID			1	Unique ID Authority					Response Date*					
nsemi												2024-05-04				
ontact Nam	ne	Title - Contact			1	Phone - Contact*				Email - Contact*						
Product-Env	v-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
uthorized R	Representative*	Title - Representative]	Phone - Representative*				Email - Representative*						
roduct-Env	v-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
R	Requester Item Number Mfr Item 1N40010		Number Mfr Item Name				Effective Date	e Version Manufacturing Site			Weight*	UOM	Unit Type			
			Ĵ	REC AXIAL 1A 50V STD			2024-05-04 CNP			250.82		mg	Each			
Ianufactu	uring Proccess Informati	on														
Те	Terminal Plating / Grid Array Material		erminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Temperatu		ure Max Time at Peak Temper		Temperat	ture Num	ber of Reflow Cy	cles			
Matte Tin (Sn) - annealed		U Alloy NA			0 C		30 seco		secon	ids 3						
omments																
or more info	formation regarding material c	omposition	please refer to	page 3												

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.18	mg	Supplier	Silicon (Si)	7440-21-3		0.1682	mg
			В	Nickel (Ni)	7440-02-0		0.0021	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0097	mg
Die Attach Solder	7.98	mg	Supplier	Silver (Ag)	7440-22-4		0.1995	mg
			А	Lead (Pb)	7439-92-1	7a	7.3815	mg
			Supplier	Tin (Sn)	7440-31-5		0.399	mg
Lead Frame	125.08	mg	Supplier	Copper (Cu)	7440-50-8		125.08	mg
Mold Compound-Black	116.8	mg		Metal Hydroxide	proprietary data		5.84	mg
			Supplier	Carbon Black (C)	1333-86-4		1.168	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		87.6	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		11.68	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		10.512	mg
Plating	0.78	mg	Supplier	Tin (Sn)	7440-31-5		0.78	mg